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## **FDP8876**

# N-Channel PowerTrench® MOSFET

**30V**, **71A**, **8.5m**Ω

## **General Descriptions**

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $r_{DS(ON)}$  and fast switching speed.



## **Features**

- $r_{DS(ON)} = 8.5 \text{m}\Omega$ ,  $V_{GS} = 10 \text{V}$ ,  $I_D = 40 \text{A}$
- $r_{DS(ON)}$  = 10.3mΩ,  $V_{GS}$  = 4.5V,  $I_D$  = 40A
- High performance trench technology for extremely low r<sub>DS(ON)</sub>
- Low gate charge
- High power and current handling capability
- RoHS Compliant







## MOSFET Maximum Ratings TA = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain to Source Voltage	30	V
$V_{GS}$	Gate to Source Voltage	±20	V
	Drain Current		
	Continuous (T <sub>C</sub> = 25°C, V <sub>GS</sub> = 10V)	70	Α
ID	Continuous ( $T_C = 25^{\circ}C$ , $V_{GS} = 4.5V$ )	64	Α
	Pulsed	Figure 4	Α
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 1)	180	mJ
$P_{D}$	Power dissipation	70	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature	-55 to 175	°C

## **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance Junction to Case TO-263	2.14	°C/W
R <sub>e,IA</sub>	Thermal Resistance Junction to Ambient TO-263,1in <sup>2</sup> copper pad area	62	°C/W

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP8876	FDP8876	TO-220AB	Tube	N/A	50 units

# Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise noted | Symbol | Parameter | Test Conditions

Symbol	Parameter	lest Con	attions	WIIN	іур	wax	Units
Off Chara	cteristics						
B <sub>VDSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{G}$	<sub>S</sub> = 0V	30	-	-	V
Zoro Coto Voltago Droin Current		$V_{DS} = 24V$				1	μΑ
DSS	Zero Gate Voltage Drain Current	$V_{GS} = 0V$	$T_A = 150^{\circ}C$	-	-	250	
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

## **On Characteristics**

	V <sub>GS(TH)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.2	-	2.5	V
	r		I <sub>D</sub> = 40A, V <sub>GS</sub> = 10V	-	6.1	8.7	
			$I_D = 40A, V_{GS} = 4.5V$	-	7.7	10.5	mΩ
	r <sub>DS(ON)</sub>	Drain to Source On Nesistance	I <sub>D</sub> = 40, V <sub>GS</sub> = 10V, T <sub>A</sub> = 175°C	-	11	14	11152

## **Dynamic Characteristics**

C <sub>ISS</sub>	Input Capacitance	\/ - 45\/ \/ -	$V_{DS} = 15V, V_{GS} = 0V,$		1700	-	pF
C <sub>OSS</sub>	Output Capacitance	_ v <sub>DS</sub> = 15ν, ν <sub>GS</sub> = _ f = 1MHz			340	-	pF
C <sub>RSS</sub>	Reverse Transfer Capacitance	1 1111112		-	210	-	pF
$R_G$	Gate Resistance		V <sub>GS</sub> =0.5V, f = 1MHz		2.3	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	V <sub>GS</sub> = 0V to 10V	V <sub>DD</sub> = 15V	-	32	45	nC
$Q_{g(5)}$	Total Gate Charge at 5V	$V_{GS} = 0V \text{ to } 5V$	I <sub>D</sub> = 40A	-	17	24	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS}$ = 0V to 1V	$I_g = 1.0 \text{mA}$	-	1.6	2.4	nC
$Q_{gs}$	Gate to Sourse Gate Charge			-	4.7	-	nC
Q <sub>gs2</sub>	Gate Charge Threshold to Plateau			-	3.1	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge			-	7.0	-	nC

## **Switching Characteristics** $(V_{GS} = 10V)$

$t_{ON}$	Turn-On Time		-	-	189	ns
t <sub>d(ON)</sub>	Turn-On Delay Time		-	9	-	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 15V, I <sub>D</sub> = 40A	-	97	-	ns
t <sub>d(OFF)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10V, $R_{GS}$ = 10 $\Omega$	-	51	-	ns
t <sub>f</sub>	Fall Time		-	39	-	ns
t <sub>OFF</sub>	Turn-Off Time		-	-	135	ns

## **Drain-Source Diode Characteristic**

V <sub>SD</sub> Source to Drain Diode Voltage	Occurs to Ducin Diada Vallage	I <sub>SD</sub> = 40A	-	-	1.25	V
	I <sub>SD</sub> = 3.2A	-	-	1.0	V	
t <sub>rr</sub>	Reverse Recovery Time	$I_{SD} = 40A$ , $dI_{SD}/dt = 100A/\mu s$	-	-	22	ns
$Q_{RR}$	Reverse Recovered Charge	I <sub>SD</sub> = 40A, dI <sub>SD</sub> /dt=100A/μs	-	-	9	nC

#### Notes:

- 1: Starting  $T_J$ =25 $^{O}$ C,L=1mH,I $_{AS}$ =19A,V $_{DD}$ =27V,V $_{GS}$ =10V
- 2: Pulse width=100s



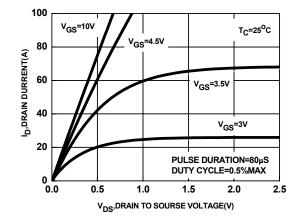


Figure 1. On Region Characteristics

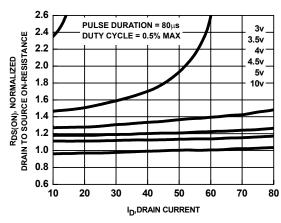


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

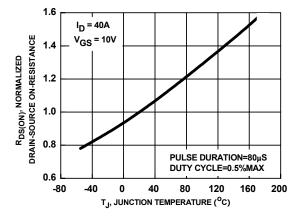


Figure 3. On Resistance Variation with Temperature

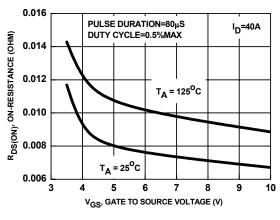


Figure 4. On-Resistance Variation with Gate-to-Source Votlage

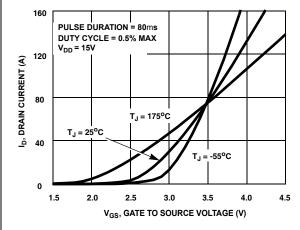


Figure 5. Transfer Characteristics

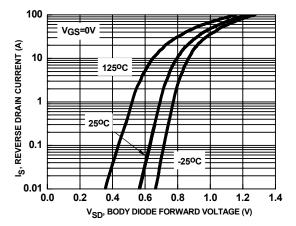


Figure 6. Body Diode Forward Voltage Variation With Source Current and Temperature



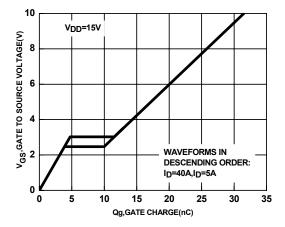


Figure 7. Gate Charge characteristics

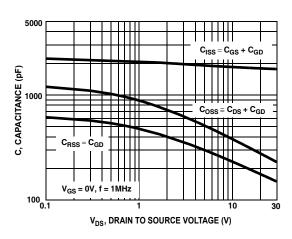


Figure 8. Saturation characteristics

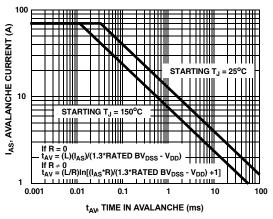


Figure 9. Unclamped Inductive Switching Capability

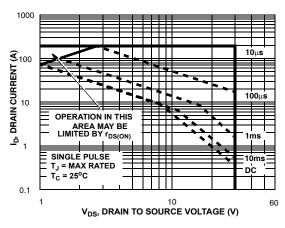


Figure 10. Safe Operating Area

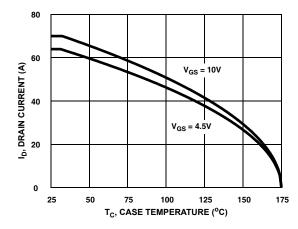


Figure 11. Maximum Continuous Drain Current vs Case Temperature

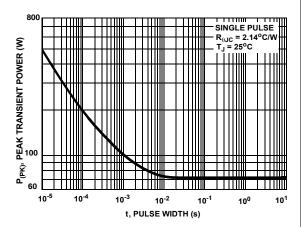


Figure 12. Normalized Drain to Source Breake Down Voltage vs Junction Temperature

## Typical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

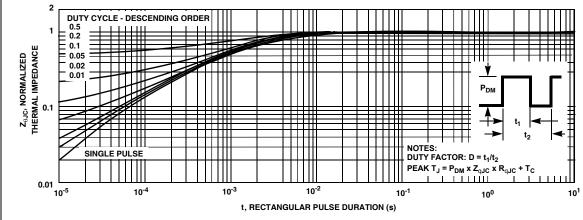


Figure 13. Normolized Maximum Transient Thermal Impedance

FDP8876 N-Channel PowerTrench® MOSFET

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